EuroCPS

Cyber-Physical Systems

A network of design centers boosting and initiating synergies between Innovative companies, industrial CPS-platforms and CPS-competency providers

SAE

Smart Anything Everywhere

Brussels event, June 13, 2016

THALES
cea
CATAPULT Connected Digital Economy
LULEÅ TEKNISKA UNIVERSITET
intel
Fraunhofer
Infineon technologies
MŰEGYETEM 1782
fine power
AVL
ST life.augmented
High Tech NL
Schneider Electric

EuroCPS in a nutshell

- SAE phase I: ICT-01-2014
- Launched: Feb 1st, 2015
- Duration: 3 years

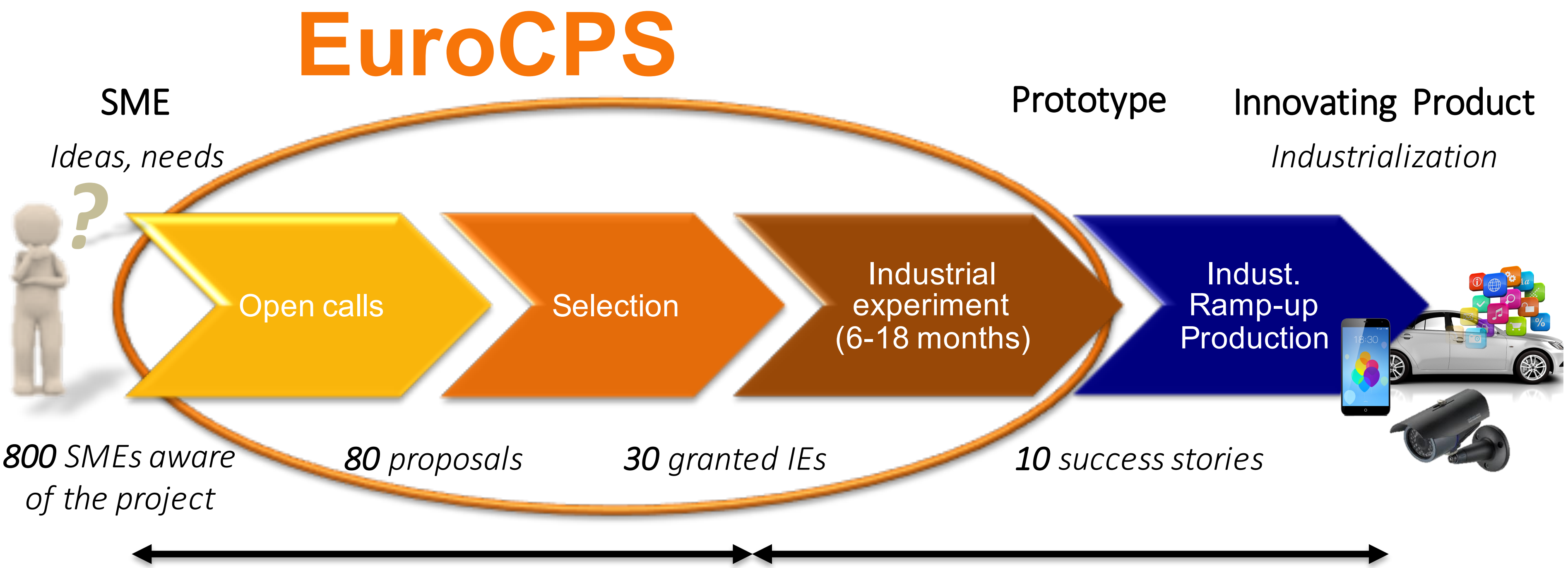
- 9 Countries
- 15 Partners
- 8 Technology Platforms (2 specifics, 6 generics)

- EC funding: 8,186,835€
- 76% supporting IEs

➲ **Enable innovative EU CPS products**

➲ **Sustain the demand for EU Manufacturing**

EuroCPS principle



EuroCPS

SME

Ideas, needs

Open calls

Selection

Industrial experiment (6-18 months)

Prototype

Indust. Ramp-up Production

Innovating Product

Industrialization

800 SMEs aware of the project

80 proposals

30 granted IEs

10 success stories

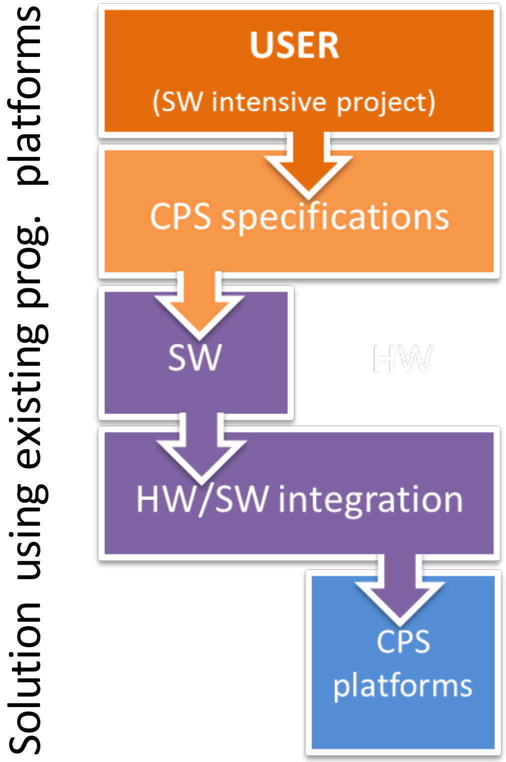
Bring **innovative CPS to business** from any sectors (Networking, Idea definition, CPS specification)

Linking user-supplier across value chains and regions (design centers = industrial technology platforms + competencies)

➲ Selected SMEs receive cascade funding, technology support to execute their IE in cooperation with competence center

EuroCPS Industrial Experiments

SW intensive project



Solution using existing prog. platforms

USER

(SW intensive project)

CPS specifications

SW

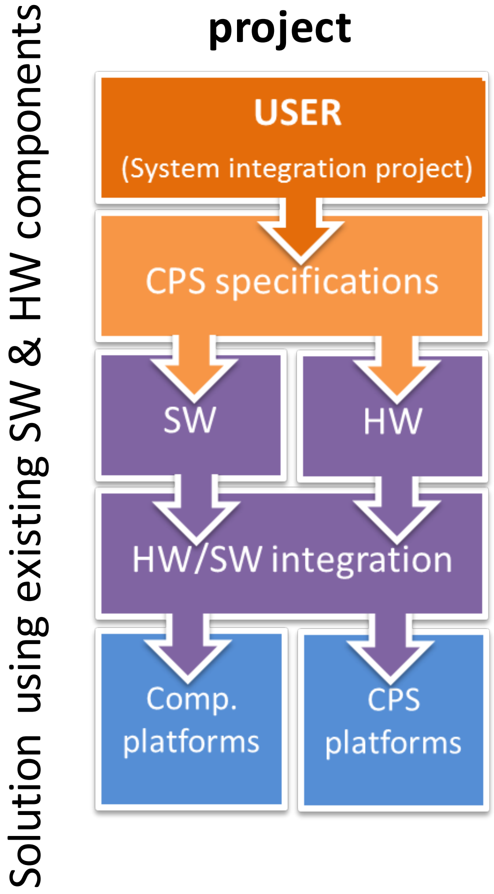
HW

HW/SW integration

CPS platforms

➲ **SW prototype demonstrator**

System integration project



Solution using existing SW & HW components

USER

(System integration project)

CPS specifications

SW

HW

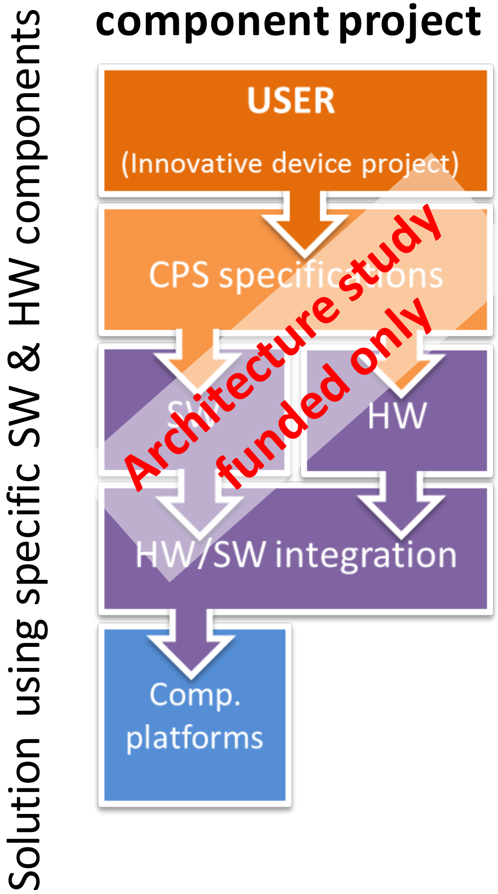
HW/SW integration

Comp. platforms

CPS platforms

➲ **Integrated system prototype demonstrator**

CPS w/ innovative component project



Solution using specific SW & HW components

USER

(Innovative device project)

CPS specifications

SW

HW

HW/SW integration

Comp. platforms

Architecture study funded only

➲ **System architecture virtual prototype demonstrator**

The 8 EuroCPS platforms

Software

Avionics Platform
Processing board & real time SW solutions provided by Thales

Integrated and Open Development Platform
Simulation methods and tools for development provided by AVL

Integration system

Connectivity Platform
Solution for digitalization application provided by Schneider

STM32 Microcontroller Platform
32-bit product range provided by STMicroelectronics

iNEMO Inertial Platform
A sensor platform provided by STMicroelectronics

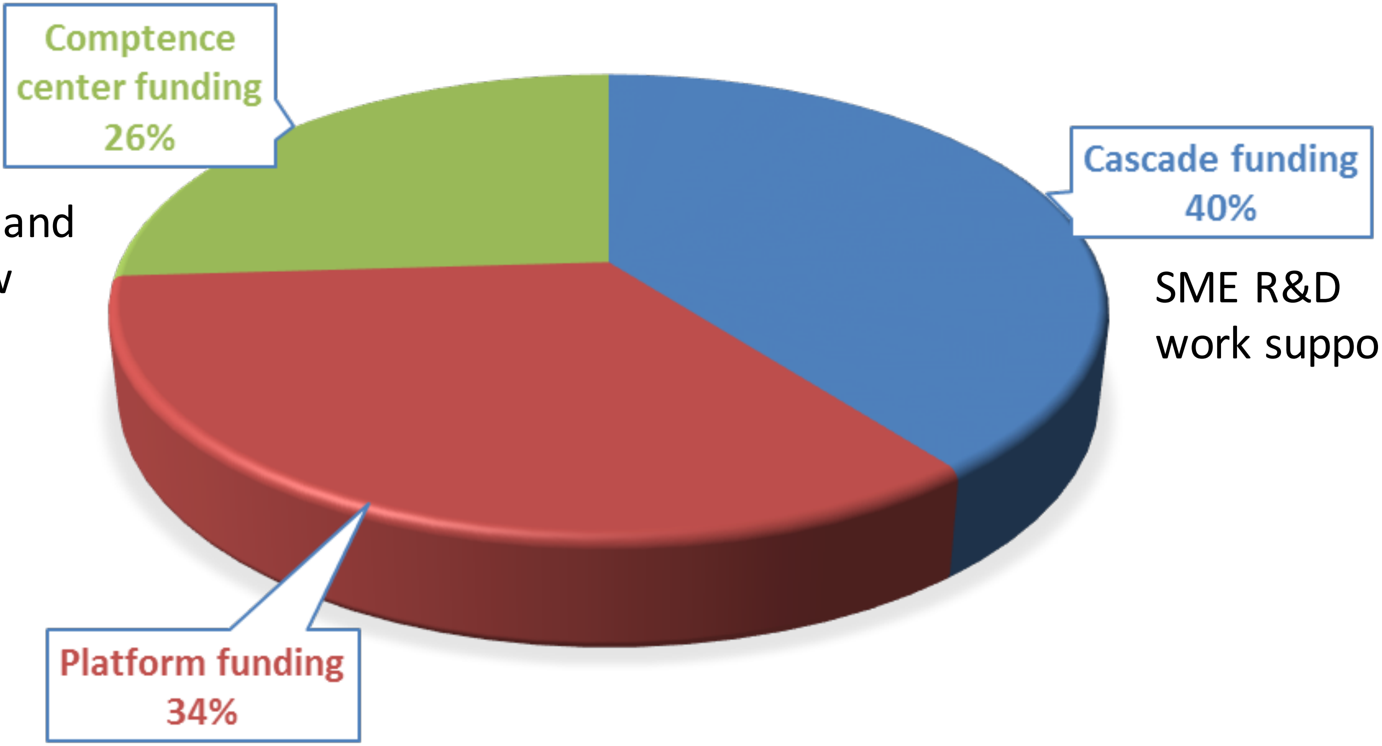
Quark System on Chip Platform
Low-power platform provided by Intel

Hardware

Power management Platform
Component platform provided by Infineon

Silicon Process and Package Technology
Leading-edge silicon processes and package technologies provided by STMicroelectronics

EuroCPS SME financial support



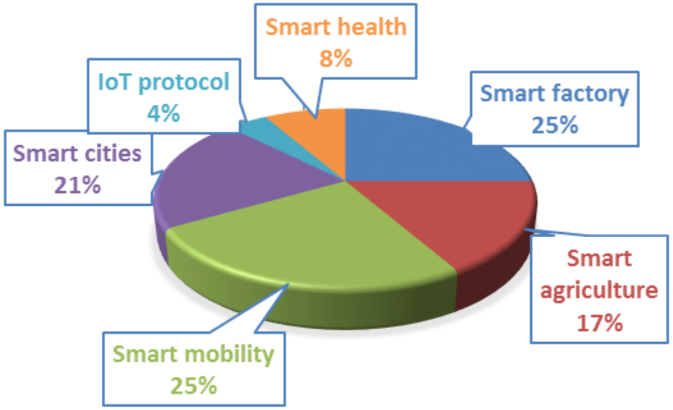
Expertise and know-how support

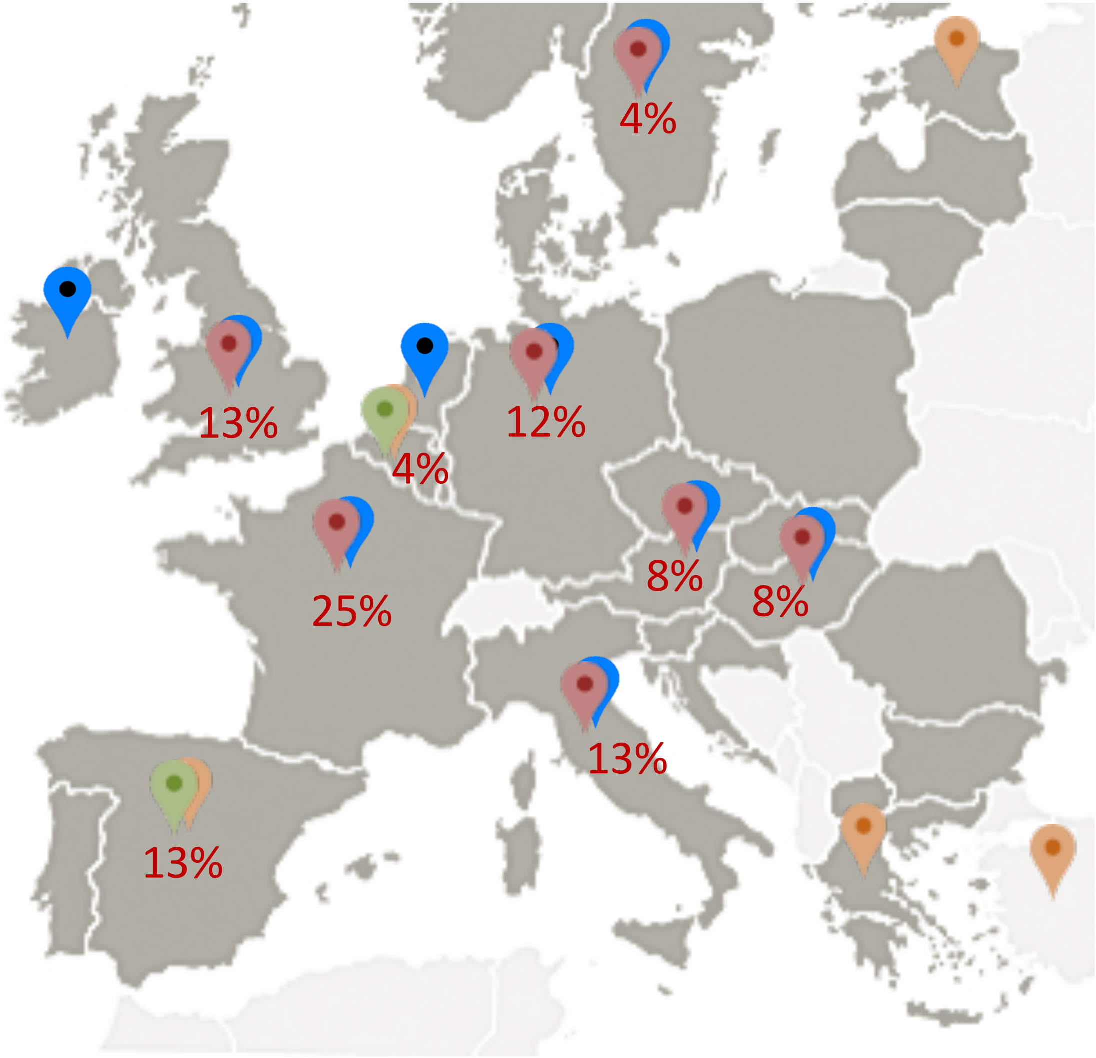
SME R&D work support

Technology access support

Granted IEs (1st and 2nd open calls)

- 72 applications
  - 📍 14 countries
  - 📍 5 not represented by a consortium member
- 24 selected IEs
  - 📍 9 granted countries
  - 📍 2 granted countries not represented by a consortium member
- IE ~ 70k€, 12 months

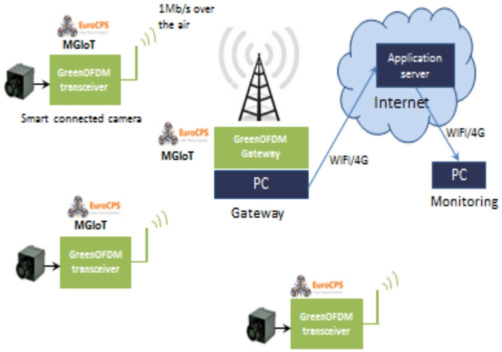




Examples of granted IEs

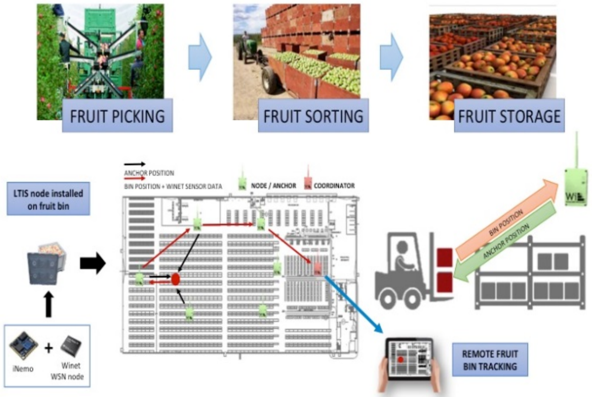
Exa-informatics

Trusted urban IoT



GreenWaves Technologies

Green OFDM IoT

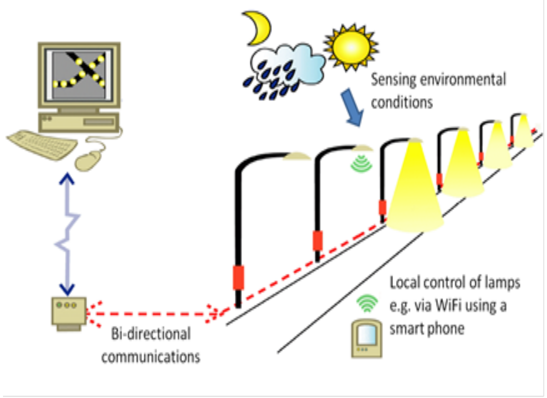


Winet

Localization and tracking for agri-food applications

Neumann

Biological sample management and tracking CPS technology

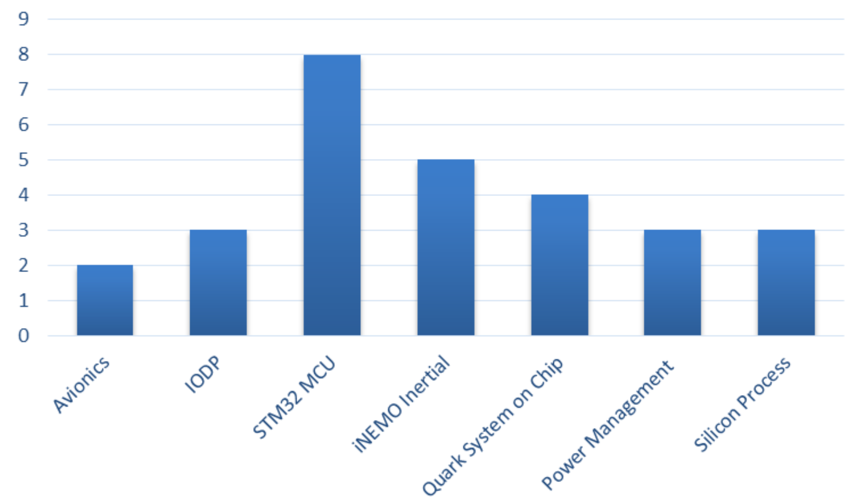


HungaroluxLight

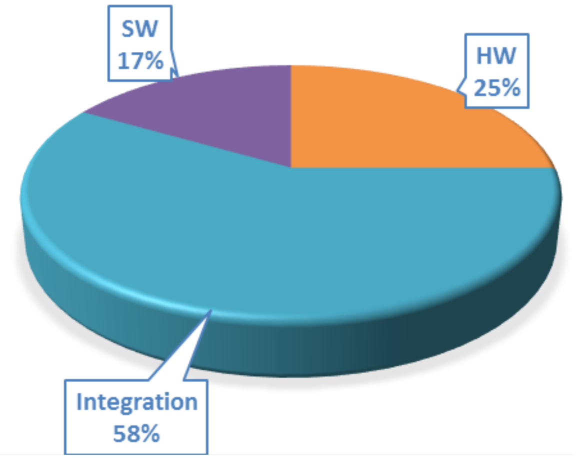
Lighting control protocol

Design centers

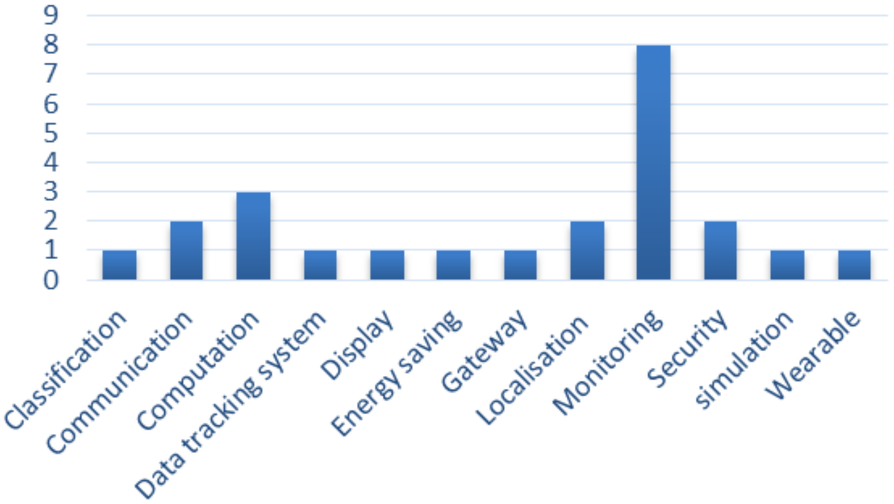
Platforms



Project types



Competencies



Summary

- EuroCPS has accomplished with success the open call phase.
- **Attractiveness** for SMEs of the proposed design center model combined with financial support is highlighted by **118 submitted applications** in total.
- **Efficiency of the model to build on open tools, platforms and standards** is demonstrated by the completion of the first two calls thanks to a tight consortium, a simple proposal procedure (5 weeks), a fast acceptance notification (7 weeks), and a short time to launch IEs.
- **24 IEs (1st and 2nd call) are currently in progress** from various business sectors and across regions. Selected 3rd open call applications will be notified on the 20th of July
- **Capacity to initiate and boost synergies** between SMEs, technology supplier and competences inside and outside their region or traditional market place is underlined by 20% of the submitted IEs coming from European countries not represented by a EuroCPS partner.

Thank you

www.eurocps.org

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